

#### **30V N-Channel MOSFET**

### **General Description**

The 40N03B is N-channel MOSFET device that features a low on-state resistance and excellent switching characteristics, and designed for low voltage high current applications such as DC/DC converter with synchronous rectifier.

### **Features**

- Simple Drive Requirement
- Low Gate Charge
- Fast Switching
- Ultra-Low RDS(on)
- Green Device Available

### **Product Summary**

BVDSS	RDSON	ID
30V	16mΩ	40A

### **Applications**

- CPU Power Delivery
- DC/DC converter
- Switching applications

# **TO-252/251 Pin Configuration**



# Absolute Maximum Ratings

Symbol	Parameter Rating  Drain-Source Voltage 30		Units
$V_{DS}$			V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current <sup>1</sup>	40	А
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current	28	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	120	Α
EAS	Single Pulse Avalanche Energy <sup>3</sup>	56	mJ
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation	45	W
T <sub>STG</sub>	T <sub>STG</sub> Storage Temperature Range -55 to 175		$^{\circ}$
$T_J$	Operating Junction Temperature Range	-55 to 175	$^{\circ}$ C

# **Thermal Data**

Symbol	Parameter Typ. Max.		Unit	
$R_{\theta JA}$	Thermal Resistance Junction-ambient		45	°C/W
$R_{ heta JC}$	Thermal Resistance Junction -Case		2.5	°C/W

# CMD40N03B/CMU40N03B



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# Electrical Characteristics ( $T_J = 25^{\circ}C$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
R <sub>DS(ON)</sub>	Static Drain Source On Resistance	$V_{GS}$ =10 $V$ , $I_D$ =10 $A$			16	mΩ
TVDS(ON)	Static Drain-Source On-Resistance	$V_{GS}$ =4.5V , $I_D$ =8A			27	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250uA$	1		3	V
-	Drain-Source Leakage Current	$V_{DS}$ =24V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			1	- uA
I <sub>DSS</sub>		$V_{DS}$ =24V , $V_{GS}$ =0V , $T_{J}$ =125 $^{\circ}$ C			10	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =10A		15		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2.1		Ω
Qg	Total Gate Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =20A		9		
Q <sub>gs</sub>	Gate-Source Charge			4.5		nC
Q <sub>gd</sub>	Gate-Drain Charge			2.6		
T <sub>d(on)</sub>	Turn-On Delay Time			8		
Tr	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$		75		
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =20A		30		ns
T <sub>f</sub>	Fall Time			25		
C <sub>iss</sub>	Input Capacitance			600		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		100		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			46		

#### **Diode Characteristics**

L	Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
	I <sub>S</sub>	Continuous Source Current <sup>1</sup>	-V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			40	Α
I	I <sub>SM</sub>	Pulsed Source Current <sup>2</sup>				120	Α
	$V_{SD}$	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =8A , T <sub>J</sub> =25℃			1	V

#### Note:

1.Limited by wire bonding

2. Pulse width limited by safe operating area

3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =20V, $V_{GS}$ =10V,L=0.5mH, $I_{AS}$ =15A

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